

Diversifying the IoT with Sub-1 GHz technology



Jeanna Copley
Product Marketing Manager

Texas Instruments

Overview

As the Internet of Things (IoT) has evolved, one of its most notable aspects has been its diversity. From a somewhat modest beginning of connecting home appliances or water/electrical meters to the Internet, the IoT is now casting a much wider shadow, reaching into retail and industrial markets such as electronic shelf labels, logistics, search and rescue, agriculture and other new application areas. Some experts expect that by **2020 50 billion devices** will be a part of the worldwide IoT.

But with every new IoT use case comes a unique set of technical operating characteristics. Fortunately, the wireless connectivity technology, Sub-1 GHz, is satisfying many of the most demanding requirements currently challenging IoT system designers. Of course, it's not any one advantage of Sub-1 GHz technology that makes it such a powerful solution for many of these applications, but rather, the combination of its considerable capabilities and their adaptability to the specific needs of the application. This paper will look at four benefits of the Sub-1 GHz technology including long range, spectrum, low power and software flexibility.

The long range of Sub-1 GHz transceivers and wireless microcontrollers (MCU) are already making possible new types of IoT applications. Some tests have shown that Sub-1 GHz transmissions have an effective range up to more than 100 kilometers (km). In addition, by occupying the ISM bands in the wireless spectrum below 1 GHz, Sub-1 GHz communications avoids the much more crowded band at 2.4 GHz, where Wi-Fi[®], Bluetooth[®] Smart, ZigBee[®] and other wireless protocols operate. On a less-busy band, IoT networks will be more robust and able to scale to cover larger areas. The added efficiency of operating in an uncrowded band, as well as several other factors, also reduce the power consumed by Sub-1 GHz devices. In fact, some

end nodes will be able to operate for up to 10 years on a coin-cell battery. Another critical characteristic is the software flexibility and compatibility of Sub-1 GHz wireless technology. Developers can quickly differentiate their products with features that bring a competitive advantage in the marketplace.

In the final analysis though, Sub-1 GHz technology is becoming one of the chief driving forces behind the IoT of the future, not just because of its unique feature set, but also because each feature is adjustable to the unique requirements of every application.

Long range wireless connectivity

The longer signaling range of wireless transceivers and integrated MCUs has set Sub-1 GHz apart from alternative technologies. This can be especially critical in IoT networks which may be quite diverse, covering entire homes or multistory office buildings, or even an entire city or region.

The effective radio frequency (RF) range of a Sub-1 GHz network will be determined by the nature of the application, which dictates the data transfer speed and the amount of data communicated. At lower data rates the range will be greater. Generally, the most advanced Sub-1 GHz end

node transceivers and integrated MCUs have been empowered with critical characteristics that enable long-range operations. For example, a recently introduced advanced wireless MCU can sense Sub-1 GHz signaling at -110 dBm at data rates of 50 kbps or, at an even slower speed of 0.625 kbps, down to -124 dBm. Interference from other wireless communications can be overcome with 90 dB of blocking and output power levels up to $+14$ dBm ensure robust signaling for longer range communications.

The diversity of today's Sub-1 GHz transceiver technology has reached a point where the specific range requirements of an IoT application can be met with a certain device. For example, narrowband and ultra-narrowband Sub-1 GHz transceivers have become a mainstay technology in applications like flow meter monitoring, police radios, alarm systems and others where the data rate can be fairly low in order to achieve longer range and the added intelligence of an MCU is not needed. In Europe, the wireless M-Bus (wM-Bus) standard for metering applications is based on narrowband Sub-1 GHz technology.

In addition to the long range qualities of narrowband and ultra-narrowband Sub-1 GHz transceivers, some advanced Sub-1 GHz wireless MCUs have an integrated long range mode of operation so the

Narrowband Sub-1 GHz

- 25-kHz bandwidth
- 12.5-kHz channel spacing
- 10-kHz channel bandwidth
- Typical applications: Meter monitoring, SIGFOX and wireless sensor networks

end node device can take advantage of the greater processing capabilities of an MCU and still achieve long range.

The architectural flexibility of Sub-1 GHz networks can also affect signaling range. Sub-1 GHz networks can be configured in any of several architectures to meet the range requirements of the applications (see Figure 1). For example, a relatively confined network with a central control point such as a home building automation system might adopt a star architecture based on wM-Bus or 6LoWPAN. A mesh architecture with multiple gateways could be employed as the basis for a larger network covering a factory campus or an agricultural operation. Additionally, another configuration is a point-to-point architecture, which might be used to communicate a small amount of data like a temperature or some other sensor measurement back to a central control element.

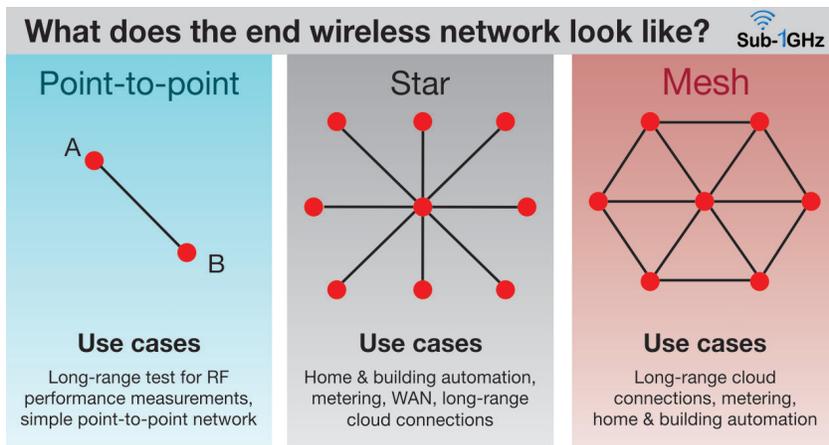


Figure 1: Examples of end wireless networks

Less crowded spectrum

Sub-1 GHz networks avoid the pitfalls of the 2.4-GHz band that are caused by overcrowding. Much of today's most popular wireless equipment operates in the 2.4-GHz band, including Wi-Fi hot spots and home

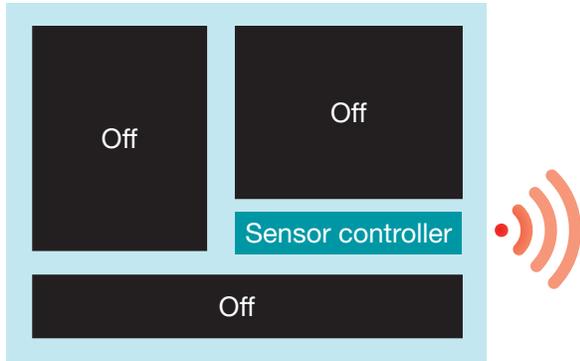


Figure 3: Sophisticated power management on some Sub-1 GHz wireless MCUs can shut down most of a sensor node to make coin-cell batteries last up to 10 years.

MCU's ARM® Cortex®-M3 core consumes as little as 51 µA of power per megahertz of processing capabilities. Moreover, the device has been integrated with sophisticated power management algorithms that will place portions of the system in a sleep mode where as little as 0.6 microamps of power is consumed while retaining the contents of memory.

Software flexibility

The software environment surrounding Sub-1 GHz networking is particularly conducive to creative innovation. Conformance to the IEEE 802.15.4g standard has given developers off-the-shelf solutions that by and large perform as expected right out of the box. In addition, open industry standards always encourage the growth of a support ecosystem of tools and development aids. For Sub-1 GHz networking these factors have accelerated the deployment of new wireless networking topologies like 6LoWPAN, wM-Bus and others.

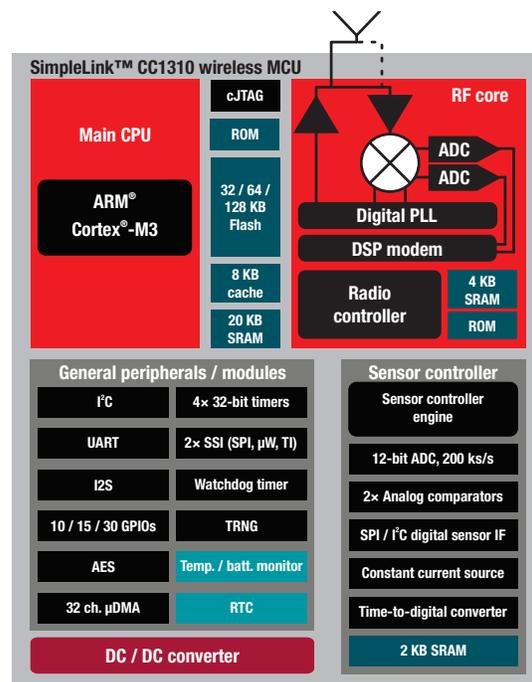
Now, newly introduced wireless Sub-1 GHz MCUs are highly programmable and resource rich, enhancing the software flexibility of end-

node devices even further (see Figure 4). Unlike simple transceivers, wireless MCUs incorporate a processing engine, such as a low-power ARM Cortex-M3 core, for application processing. The ease with which these wireless MCUs can be programmed allows end-node device designers and equipment manufacturers to rapidly integrate differentiating functionality into their products, functionality that will make their products stand apart in competitive situations.

The most advanced of such wireless MCUs have been empowered with a full complement of resources that simplify software development. The

TI's ultra-low power wireless MCU

The extremely adaptable SimpleLink™ Sub-1 GHz **CC1310 wireless MCU** includes an ARM® Cortex®-M3 core, ultra-low power RF, peripherals and an integrated sensor controller engine that saves power by waking up the rest of the device only when needed.



inclusion of a real-time operating system, drivers, peripheral interfaces and, at least in one case, a sensor controller means that software developers can concentrate on developing innovative new features and not worry about how they are going to integrate basic resources into the device.

In addition, this sort of software environment is also a tremendous benefit to networking equipment suppliers who wish to deploy their own proprietary software. Programming tools, development platforms, libraries of intellectual property and other support features will accelerate the time-to-market for new proprietary systems.

Conclusions

The IoT of the future will be an exciting place. Every day creative developers are generating ideas for innovative new IoT applications, causing a groundswell of demand for wireless connectivity technology with new capabilities and feature sets. And Sub-1 GHz is responding. Sub-1 GHz transceivers and wireless MCUs provide the capabilities needed by next-generation IoT systems and, just as importantly, this functionality is adaptable to the one-of-a-kind requirements of each and every application.

Important Notice: The products and services of Texas Instruments Incorporated and its subsidiaries described herein are sold subject to TI's standard terms and conditions of sale. Customers are advised to obtain the most current and complete information about TI products and services before placing orders. TI assumes no liability for applications assistance, customer's applications or product designs, software performance, or infringement of patents. The publication of information regarding any other company's products or services does not constitute TI's approval, warranty or endorsement thereof.

SimpleLink is a trademark of Texas Instruments. All other trademarks are the property of their respective owners.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com